

## DESCRIPTION

The MP2317 is a high-efficiency, synchronous, rectified, step-down, switch-mode converter with built-in internal power MOSFETs. It offers a very compact solution that achieves 1A of continuous output current with excellent load and line regulation over a wide input supply range.

The MP2317's switching edge is optimized for low EMI. SW anti-ringing is employed to address high-frequency radiation EMI issues.

Full protection features include over-current protection (OCP) and thermal shutdown.

The MP2317 requires a minimum number of readily available, standard, external components and is available in a space-saving, 6-pin, TSOT23 package.

## FEATURES

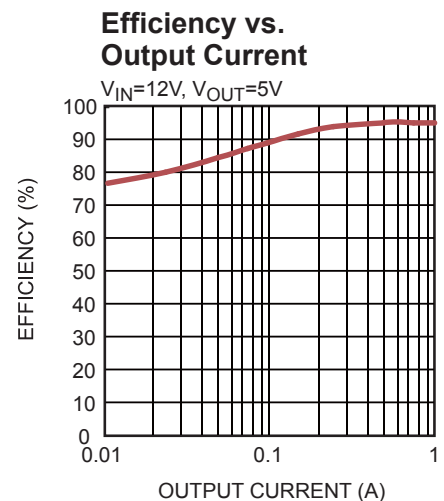
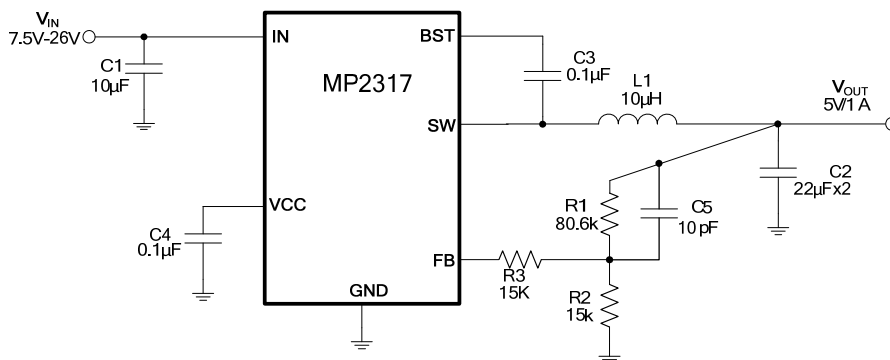
- Wide 7.5V to 26V Operating Input Range
- 1A Load Current
- 100mΩ/50mΩ Low  $R_{DS(ON)}$  Internal Power MOSFETs
- Internal Power-Save Mode for Light Load
- 600kHz Fixed Switching Frequency at CCM
- Optimized for Low EMI
- Internal Soft Start
- Over-Current Protection (OCP) and Hiccup
- Thermal Shutdown
- Output Adjustable from 3.3V
- Available in a TSOT23-6 Package

## APPLICATIONS

- Stand-By Power Supply
- White Goods
- Flat-Panel Television and Monitors

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## TYPICAL APPLICATION



## ORDERING INFORMATION

Part Number*	Package	Top Marking
MP2317GJ	TSOT23-6	<i>See Below</i>

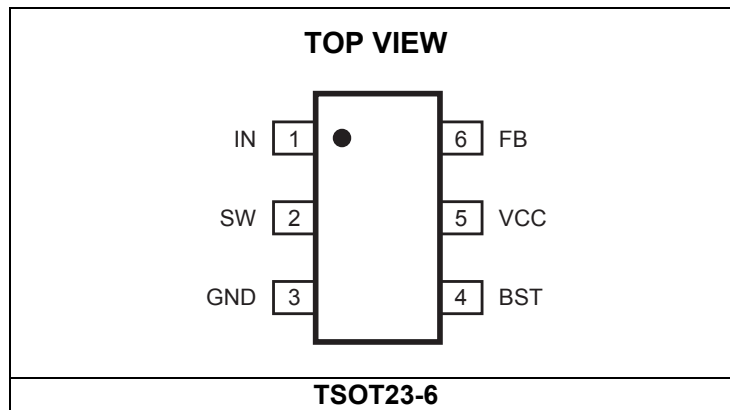
\* For Tape & Reel, add suffix -Z (e.g. MP2317GJ-Z)

## TOP MARKING

**| AQR Y**

AQR: Product code of MP2317GJ  
 Y: Year code

## PACKAGE REFERENCE



**ABSOLUTE MAXIMUM RATINGS <sup>(1)</sup>**

$V_{IN}$ .....	-0.3V to +28V
$V_{SW}$ .....	-0.6V (-5V < 10ns) to +28V (30V < 10ns)
$V_{BST}$ .....	$V_{SW} + 6V$
All other pins .....	-0.3V to +6V
Continuous power dissipation ( $T_A = +25^\circ C$ ) <sup>(2)</sup>	1.25W
Junction temperature .....	150°C
Lead temperature .....	260°C
Storage temperature .....	-65°C to 150°C

**Recommended Operating Conditions <sup>(3)</sup>**

Supply voltage ( $V_{IN}$ ) .....	7.5V to 26V
Output voltage ( $V_{OUT}$ ).....	3.3V to $V_{IN} \times D_{MAX}$
Operating junction temp ( $T_J$ )....	-40°C to +125°C

<b>Thermal Resistance <sup>(4)</sup></b>	<b><math>\theta_{JA}</math></b>	<b><math>\theta_{JC}</math></b>	
TSOT23-6.....	100.....	55.....	°C/W

**NOTES:**

- 1) Exceeding these ratings may damage the device.
- 2) The maximum allowable power dissipation is a function of the maximum junction temperature  $T_J$  (MAX), the junction-to-ambient thermal resistance  $\theta_{JA}$ , and the ambient temperature  $T_A$ . The maximum allowable continuous power dissipation at any ambient temperature is calculated by  $P_D$  (MAX) =  $(T_J$  (MAX) -  $T_A$ ) /  $\theta_{JA}$ . Exceeding the maximum allowable power dissipation produces an excessive die temperature, causing the regulator to go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- 3) The device is not guaranteed to function outside of its operating conditions.
- 4) Measured on JESD51-7, 4-layer PCB.

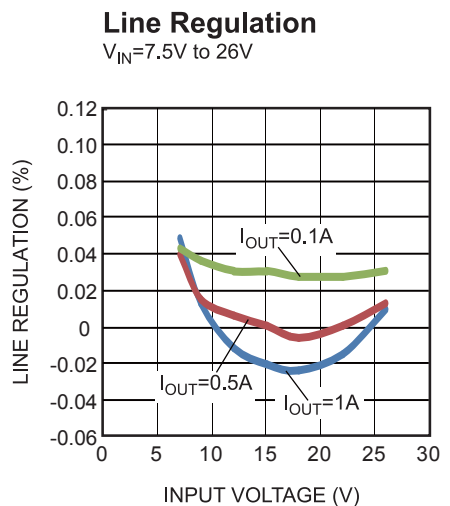
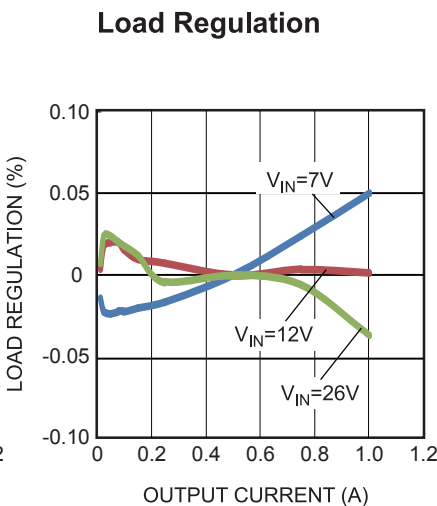
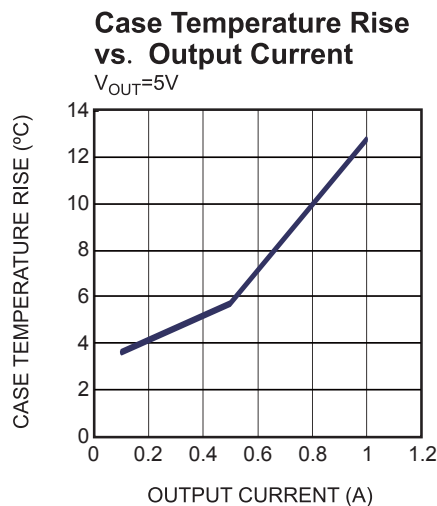
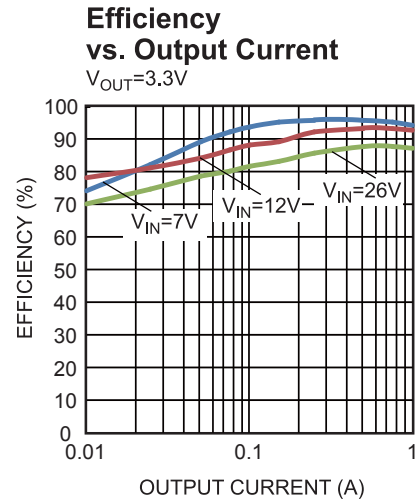
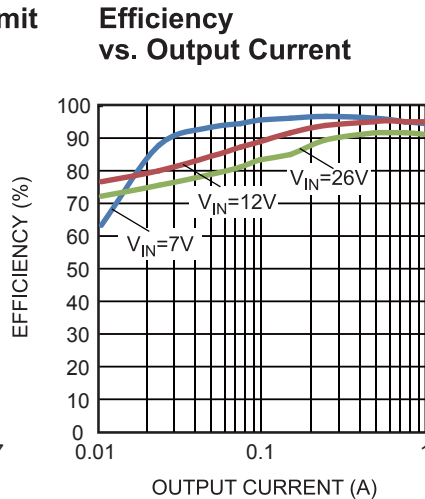
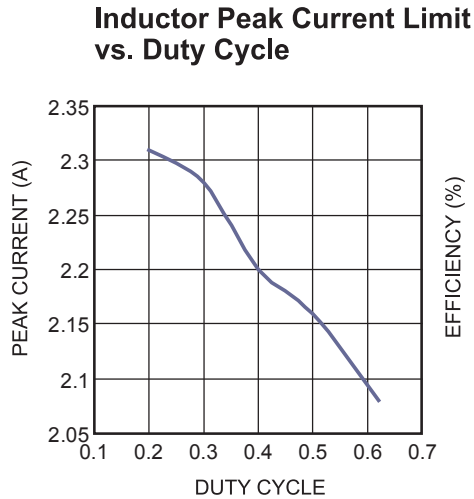
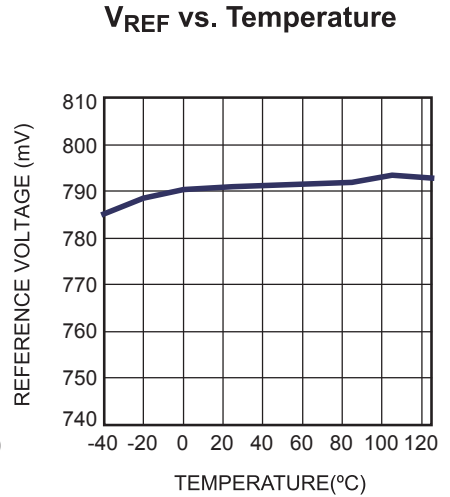
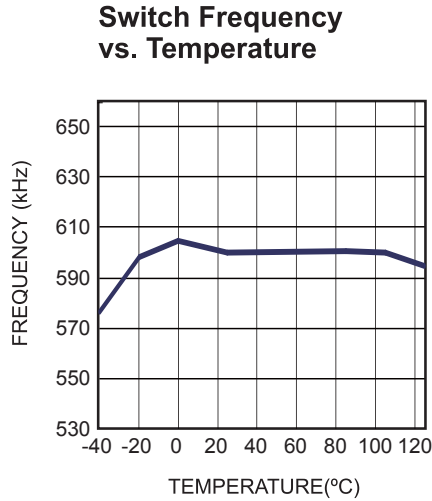
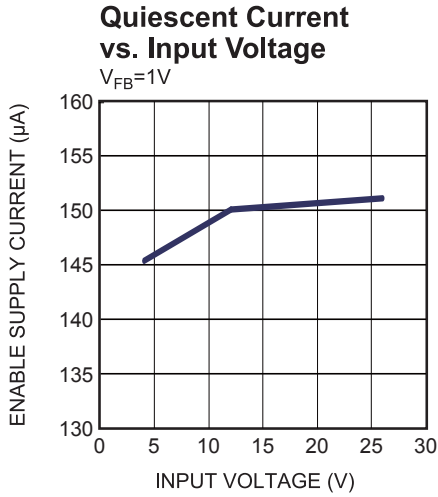
## ELECTRICAL CHARACTERISTICS

$V_{IN} = 12V$ ,  $T_J = -40^{\circ}C$  to  $125^{\circ}C$ <sup>(5)</sup>, unless otherwise noted. Typical value is based on the average value when  $T_J = 25^{\circ}C$ .

Parameter	Symbol	Condition	Min	Typ	Max	Units
Supply current (quiescent)	$I_q$	$V_{FB} = 1V$		150		$\mu A$
HS switch-on resistance	$HS_{RDS-ON}$	$V_{BST-SW} = 4V$		100		m $\Omega$
LS switch-on resistance	$LS_{RDS-ON}$	$V_{CC} = 4V$		50		m $\Omega$
Switch leakage	$SW_{LKG}$				1	$\mu A$
Current limit	$I_{LIMIT}$	Duty cycle = 40%, $T_J = 25^{\circ}C$	1.4	2.2	3	A
Oscillator frequency	$f_{SW}$	$V_{FB} = 750mV$	500	600	700	kHz
Foldback frequency	$f_{FB}$	$V_{FB} = 200mV$		0.2		$f_{SW}$
Maximum duty cycle	$D_{MAX}$	$V_{FB} = 750mV$		93		%
Minimum on time <sup>(6)</sup>	$T_{ON MIN}$			90		ns
Feedback voltage	$V_{FB}$		775	791	807	mV
Feedback current	$I_{FB}$	$V_{FB} = 820mV$		10	50	nA
$V_{IN}$ under-voltage lockout threshold rising	$INUV_{Vth}$		5.2	6.3	7.5	V
$V_{IN}$ under-voltage lockout threshold hysteresis	$INUV_{HYS}$			500		mV
VCC regulator	$V_{CC}$			4		V
VCC load regulation		$I_{CC} = 5mA$		1.5		%
Soft-start period	$T_{SS}$	10% to 90%	0.8	1.5	2.2	ms
Thermal shutdown <sup>(6)</sup>	$T_{SD}$			150		$^{\circ}C$
Thermal hysteresis <sup>(6)</sup>	$T_{SD HYS}$			20		$^{\circ}C$

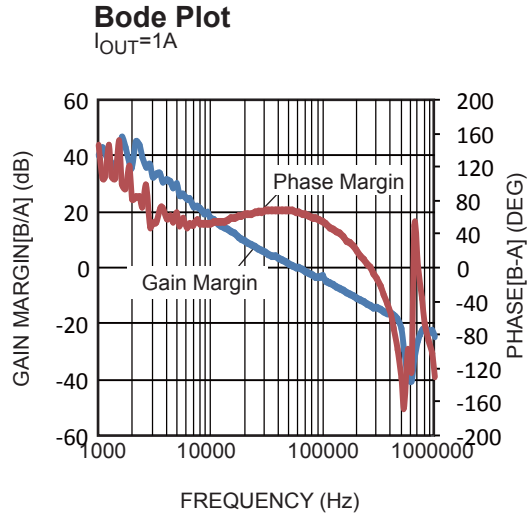
### NOTES:

- 5) Not tested in production and guaranteed by over-temperature correlation.  
 6) Guaranteed by design and characterization test.

**TYPICAL PERFORMANCE CHARACTERISTICS**
 $V_{IN} = 12V$ ,  $V_{OUT} = 5V$ ,  $L = 10\mu H$ ,  $T_A = 25^\circ C$ , unless otherwise noted.


**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

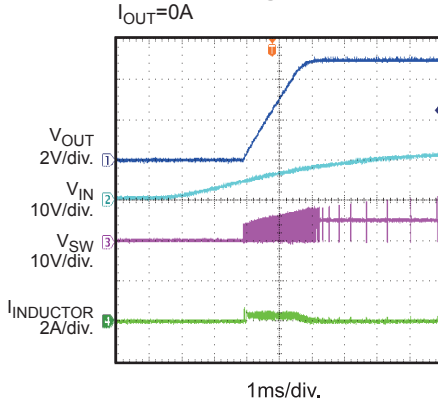
$V_{IN} = 12V$ ,  $V_{OUT} = 5V$ ,  $L = 10\mu H$ ,  $T_A = 25^\circ C$ , unless otherwise noted.



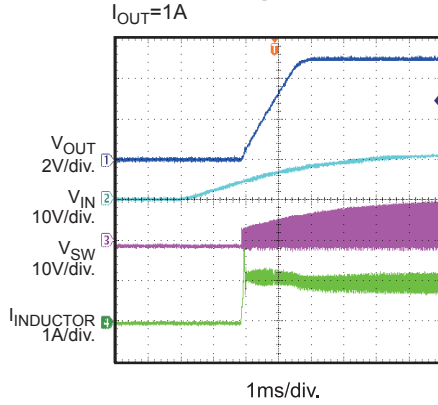
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**

$V_{IN} = 12V$ ,  $V_{OUT} = 5V$ ,  $L = 10\mu H$ ,  $T_A = 25^\circ C$ , unless otherwise noted.

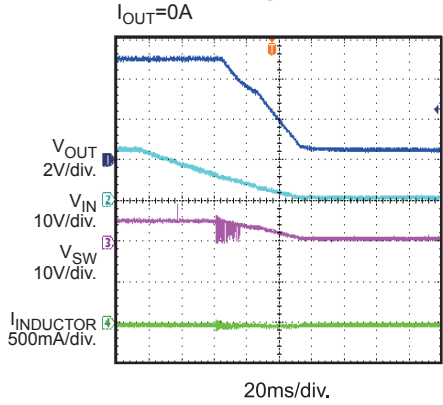
**Start-Up through Input Voltage**  
 $I_{OUT}=0A$



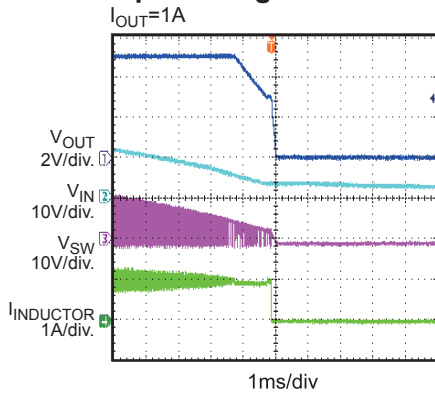
**Start-Up through Input Voltage**  
 $I_{OUT}=1A$



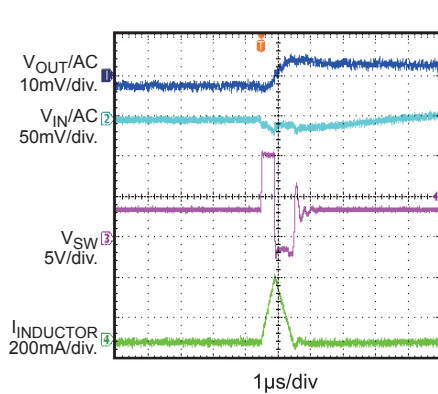
**Shutdown through Input Voltage**  
 $I_{OUT}=0A$



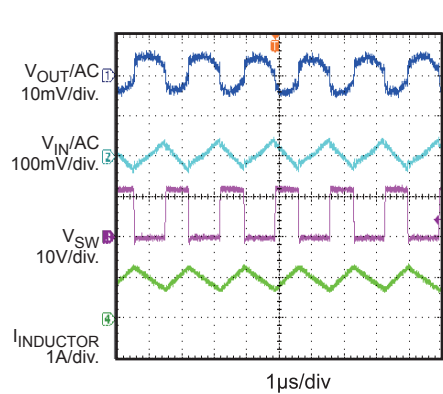
**Shutdown through Input Voltage**  
 $I_{OUT}=1A$



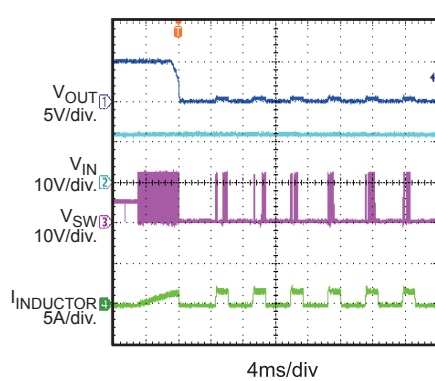
**Input/Output Ripple**  
 $I_{OUT}=0A$



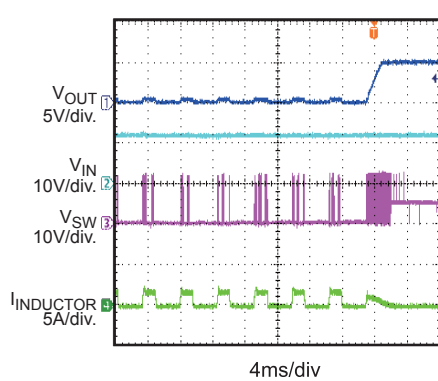
**Input/Output Ripple**  
 $I_{OUT}=1A$



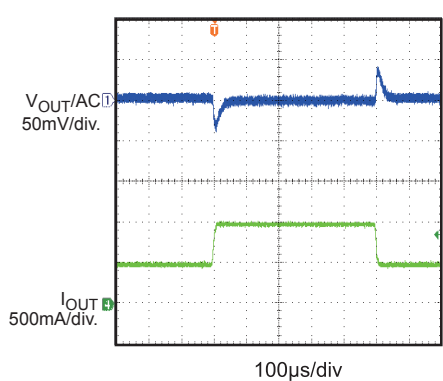
**OCP Entry**  
 $I_{OUT}=0A$



**OCP Recovery**  
 $I_{OUT}=0A$



**Load Transient Response**  
 $I_{OUT}=0.5A$  to  $1A$



## PIN FUNCTIONS

Package Pin #	Name	Description
1	IN	<b>Supply voltage.</b> The MP2317 operates from a +7.5V to +26V input rail. C1 is needed to decouple the input rail. Connect using wide PCB traces.
2	SW	<b>Switch output.</b> Connect using wide PCB traces.
3	GND	<b>System ground.</b> GND is the reference ground of the regulated output voltage. GND requires special consideration during PCB layout. Connect GND with copper traces and vias.
4	BST	<b>Bootstrap.</b> Connect a capacitor between SW and BST to form a floating supply across the high-side switch driver.
5	VCC	<b>Internal LDO output.</b> Decouple VCC with a 0.1 $\mu$ F - 0.22 $\mu$ F capacitor. VCC can be biased by an external 5V output voltage through a diode.
6	FB	<b>Feedback.</b> An external resistor divider from the output to GND tapped to FB sets the output voltage. To prevent a current-limit runaway during a short-circuit fault condition, the frequency foldback comparator lowers the oscillator frequency when the FB voltage is below 396mV.



BLOCK DIAGRAM

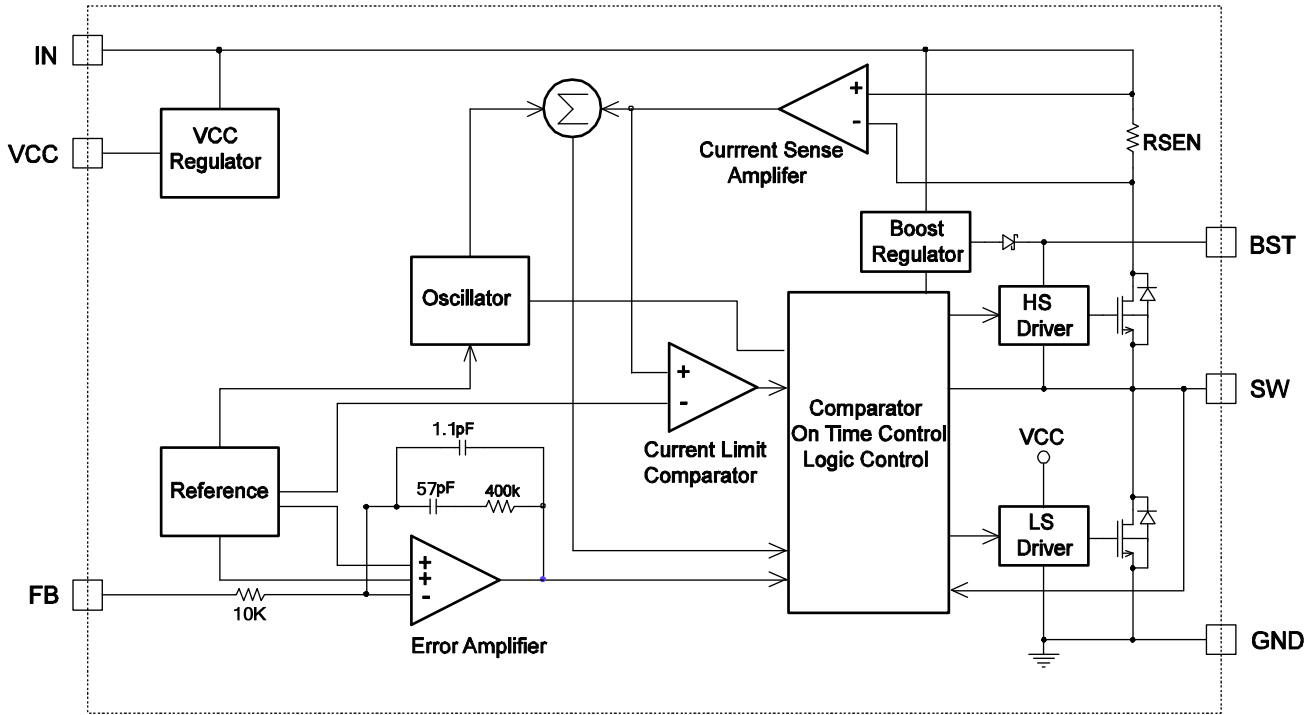


Figure 1: Functional Block Diagram

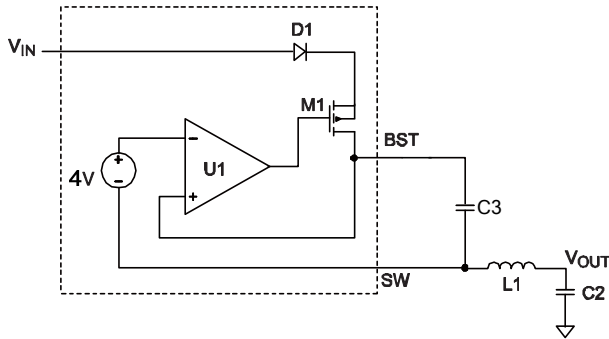


**Thermal Shutdown**

Thermal shutdown prevents the chip from operating at exceedingly high temperatures. When the silicon die temperature is higher than 150°C, the entire chip shuts down. When the temperature is below its lower threshold, typically 130°C, the chip is enabled again.

**Floating Driver and Bootstrap Charging**

The floating power MOSFET driver is powered by an external bootstrap capacitor. This floating driver has its own UVLO protection. This UVLO's rising threshold is 2.2V with a hysteresis of 150mV. The bootstrap capacitor voltage is regulated internally by  $V_{IN}$  through D1, C3, L1, and C2 (see Figure 3). If  $V_{IN} - V_{SW}$  is more than 4V, U2 regulates M3 to maintain a 4V BST voltage across C3.



**Figure 3: Internal Bootstrap Charging**

**Circuit Start-Up and Shutdown**

If  $V_{IN}$  is higher than its UVLO threshold, the chip starts up. The reference block starts first, generating a stable reference voltage and current, and then the internal regulator is enabled. The regulator provides a stable supply for the remaining circuitries.

In the shutdown procedure, the signaling path is first blocked to prevent any fault triggering.  $V_{COMP}$  and the internal supply rail are then pulled down. The floating driver is not subject to this shutdown command.

## APPLICATION INFORMATION

### Setting the Output Voltage

The external resistor divider is used to set the output voltage (see the Typical Application on page 1). The feedback resistor (R1) also sets the feedback loop bandwidth with the external compensation capacitor. Calculate R2 with Equation (1):

$$R2 = \frac{R1}{\frac{V_{OUT}}{0.791V} - 1} \quad (1)$$

Table 1 lists the recommended resistor values for common output voltages.

**Table 1: Resistor Selection for Common Output Voltages**

V <sub>OUT</sub> (V)	R1 (kΩ)	R2 (kΩ)	Lo (μH)
3.3	80.6	25.5	10
5	80.6	15	10

### Selecting the Inductor

A 1μH to 22μH inductor with a DC current rating at least 25% percent higher than the maximum load current is recommended for most applications. For highest efficiency, the inductor DC resistance should be less than 30mΩ. For most designs, the inductance value can be derived from Equation (2):

$$L_1 = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} \times \Delta I_L \times f_{OSC}} \quad (2)$$

Where ΔI<sub>L</sub> is the inductor ripple current.

Choose the inductor current to be approximately 30% of the maximum load current. The maximum inductor peak current can be calculated with Equation (3):

$$I_{L(MAX)} = I_{LOAD} + \frac{\Delta I_L}{2} \quad (3)$$

Under light-load conditions below 100mA, a larger inductance is recommended for improved efficiency.

### Selecting the Input Capacitor

The input current to the step-down converter is discontinuous, and therefore requires a capacitor to supply AC current to the step-down converter while maintaining the DC input voltage. For best performance, use low ESR capacitors. Ceramic capacitors with X5R or

X7R dielectrics are highly recommended because of their low ESR and small temperature coefficients. For most applications, a 22μF capacitor is sufficient.

Since the input capacitor (C1) absorbs the input switching current, it requires an adequate ripple current rating. The RMS current in the input capacitor can be estimated with Equation (4):

$$I_{C1} = I_{LOAD} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)} \quad (4)$$

The worst-case condition occurs at V<sub>IN</sub> = 2V<sub>OUT</sub>, shown in Equation (5):

$$I_{C1} = \frac{I_{LOAD}}{2} \quad (5)$$

For simplification, choose an input capacitor with an RMS current rating greater than half of the maximum load current.

The input capacitor can be electrolytic, tantalum, or ceramic. When using electrolytic or tantalum capacitors, a small, high-quality ceramic capacitor (i.e.: 1μF) should be placed as close to the IC as possible. When using ceramic capacitors, ensure that they have enough capacitance to provide a sufficient charge to prevent excessive voltage ripple at the input. The input voltage ripple caused by capacitance can be estimated with Equation (6):

$$\Delta V_{IN} = \frac{I_{LOAD}}{f_s \times C1} \times \frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \quad (6)$$

### Selecting the Output Capacitor

The output capacitor (C2) is required to maintain the DC output voltage. Ceramic, tantalum, or low ESR electrolytic capacitors are recommended. For best results, use low ESR capacitors to keep the output voltage ripple low. The output voltage ripple can be estimated with Equation (7):

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_s \times L_1} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \times \left(R_{ESR} + \frac{1}{8 \times f_s \times C2}\right) \quad (7)$$

Where L<sub>1</sub> is the inductor value and R<sub>ESR</sub> is the equivalent series resistance (ESR) value of the output capacitor.

For ceramic capacitors, the impedance at the switching frequency is dominated by the capacitance, which mainly causes the output voltage ripple. For simplification, the output voltage ripple can be estimated with Equation (8):

$$\Delta V_{OUT} = \frac{V_{OUT}}{8 \times f_s^2 \times L_1 \times C_2} \times \left( 1 - \frac{V_{OUT}}{V_{IN}} \right) \quad (8)$$

In the case of tantalum or electrolytic capacitors, the ESR dominates the impedance at the switching frequency. For simplification, the output ripple can be approximated with Equation (9):

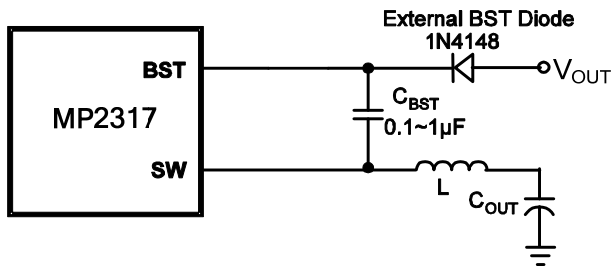
$$\Delta V_{OUT} = \frac{V_{OUT}}{f_s \times L_1} \times \left( 1 - \frac{V_{OUT}}{V_{IN}} \right) \times R_{ESR} \quad (9)$$

The characteristics of the output capacitor also affect the stability of the regulation system. The MP2317 can be optimized for a wide range of capacitance and ESR values.

**External Bootstrap Diode**

An optional, external diode may enhance the efficiency of the regulator. The conditions of the external diode are applied when the output voltage is 5V.

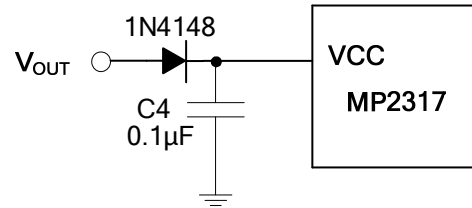
In this case, it is recommended to connect an external BST diode from V<sub>OUT</sub> to BST (see Figure 4).



**Figure 4: Optional External Bootstrap Diode Added to Enhance Efficiency**

**External VCC Diode**

When V<sub>OUT</sub> is 5V, an external optional diode from V<sub>OUT</sub> to VCC may enhance the efficiency of the regulator (see Figure 5).



**Figure 5: Optional External Diode Added to Enhance Efficiency**

### PCB Layout Guidelines <sup>(7)</sup>

Efficient PCB layout is critical for stable operation. For best results, refer to Figure 6 and follow the guidelines below.

1. Keep the connection of the input ground and GND as short and wide as possible.
2. Connect the ground of the VCC capacitor to the IC's GND through multiple vias or wide traces.
3. Keep the connection of the input capacitor and IN as short and wide as possible.
4. Ensure that all feedback connections are short and direct.
5. Place the feedback resistors and compensation components as close to the chip as possible.
6. Route SW away from sensitive analog areas such as FB.

**NOTE:**

- 7) The recommended layout is based on Figure 8: Typical Application Circuit.

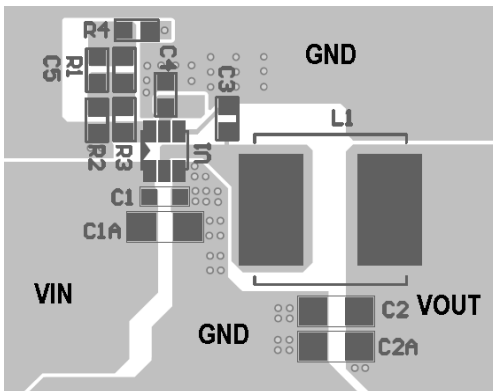
### Design Example

Table 2 is a design example following the application guidelines for the specifications below:

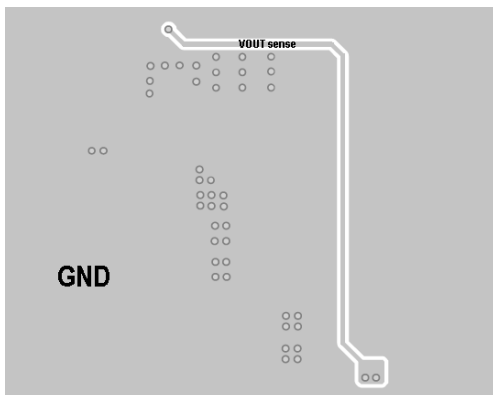
**Table 2: Design Example**

$V_{IN}$	12V
$V_{OUT}$	5V
$I_O$	1A

The detailed application schematics are shown in Figure 7 and Figure 8. The typical performance and circuit waveforms are shown in the Typical Performance Characteristics section. For more device applications, please refer to the related evaluation board datasheets.



**Top Layer**



**Bottom Layer**

**Figure 6: Recommended PCB Layout**

TYPICAL APPLICATION CIRCUITS

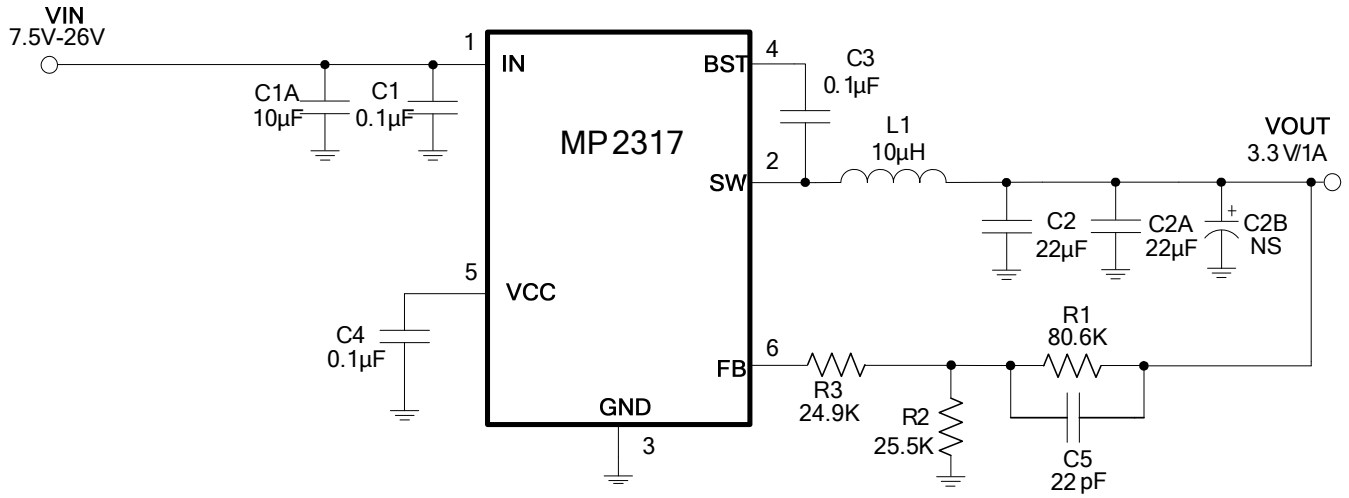


Figure 7: 3.3V/1A Output

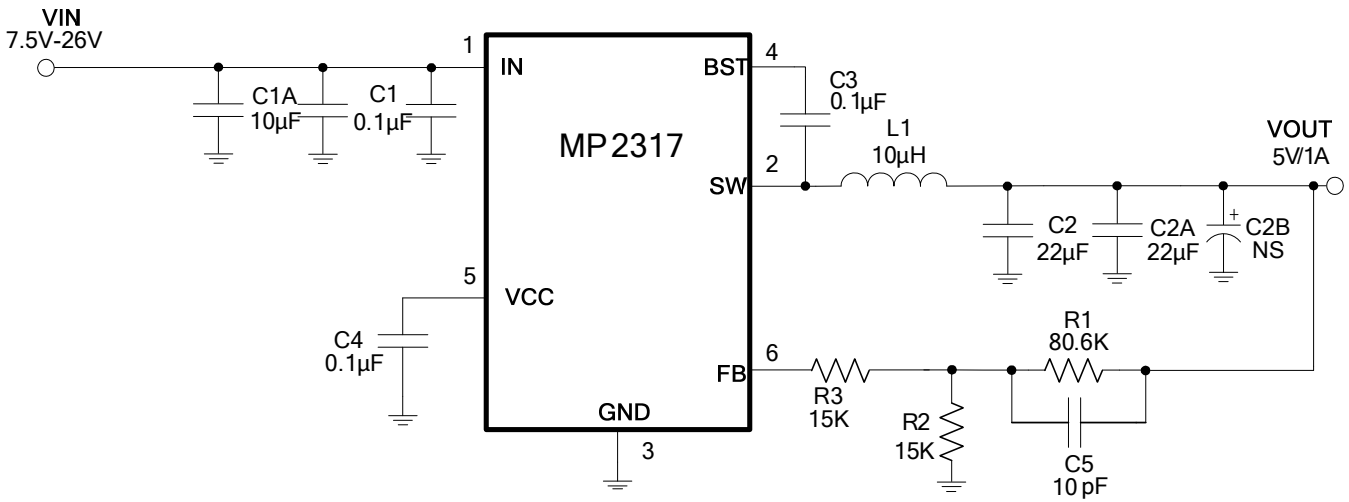
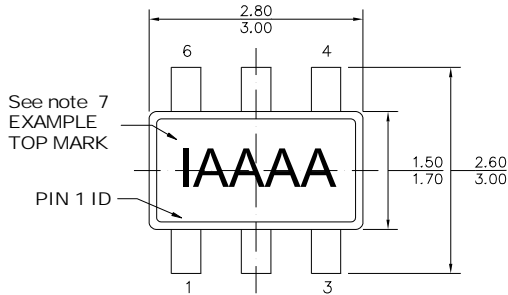
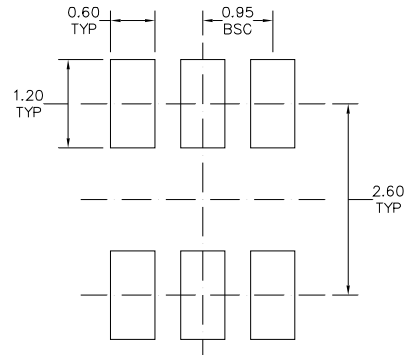
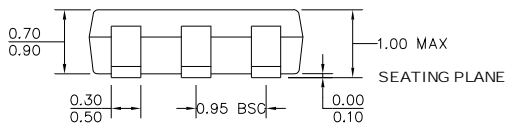
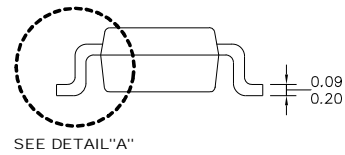
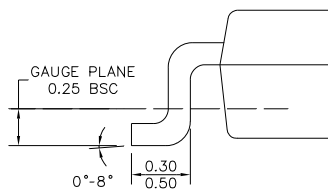


Figure 8: 5V/1A Output

**PACKAGE INFORMATION**
**TSOT23-6**

TOP VIEW

RECOMMENDED LAND PATTERN

FRONT VIEW

SIDE VIEW
**NOTE:**

DETAIL "A"

- 1) ALL DIMENSIONS ARE IN MILLIMETERS
- 2) PACKAGE LENGTH DOES NOT INCLUDE MOLD FLASH PROTRUSION OR GATE BURR
- 3) PACKAGE WIDTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION
- 4) LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.10 MILLIMETERS MAX
- 5) DRAWING CONFORMS TO JEDEC MO-193, VARIATION AB
- 6) DRAWING IS NOT TO SCALE
- 7) PIN 1 IS LOWER LEFT PIN WHEN READING TOP MARK FROM LEFT TO RIGHT, (SEE EXAMPLE TOP MARK)

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